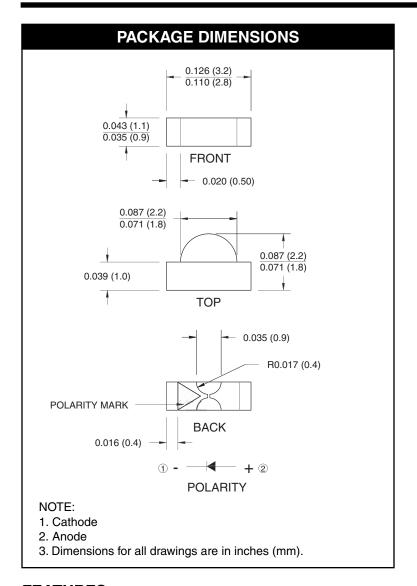
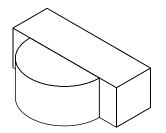


QTLP610CIR





FEATURES

- · Right Angle Surface Mount Package
- Available in 0.315" (8mm) width tape on 7" (178mm) diameter reel; 2,000 units per reel
- Wide Viewing Angle 160°
- Wavelength = 940 nm, GaAs
- Water Clear Lens
- Matched Photosensor: QTLP610CPD



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ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise specified)							
Parameter	Symbol	Rating	Unit				
Operating Temperature	T _{OPR}	-40 to +85	°C				
Storage Temperature	T _{STG}	-40 to +90	°C				
Soldering Temperature (Iron) ^(1,2,3)	T _{SOL-I}	240 for 5 sec	°C				
Soldering Temperature (Flow) ^(1,2)	T _{SOL-F}	260 for 10 sec	°C				
Continuous Forward Current	I _F	65	mA				
Reverse Voltage	V _R	5	V				
Power Dissipation ⁽⁴⁾	P _D	100	mW				
Peak Forward Current (Pulse width = 100µs, Duty Cycle=1%)	I _{FD}	1.0	А				

Notes:

- 1. RMA flux is recommended.
- 2. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 3. Soldering iron tip at 1/16" (1.6mm) from housing
- 4. At 25°C or below

ELECTRICAL / OPTICAL CHARACTERISTICS (T _A =25°C)									
PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNITS			
Peak Emission Wavelength	I _F = 20 mA	λР	_	940	_	nm			
Emission Angle	I _F = 20 mA	Θ	_	±80	_	Deg.			
Forward Voltage	I _F = 20 mA	V _F	_	1.2	1.5	V			
	$I_F = 100 \text{ mA}, t_P = 100 \mu \text{s}, \text{ Duty Cycle} = 0.01$		_	1.4	1.85				
	I _F = 1 A, t _P = 100 μs, Duty Cycle = 0.01		_	2.6	4.0				
Reverse Current	V _R = 5 V	I _R	_	_	10	μΑ			
Radiant Intensity	I _F = 20 mA		0.5	0.8	_				
	$I_F = 100 \text{ mA}, t_P = 100 \mu \text{s}, \text{ Duty Cycle} = 0.01$	Ee	_	4.0	_	mW/sr			
	I _F = 1 A, t _P = 100 μs, Duty Cycle = 0.01		_	40	_				
Rise Time	I _F = 100 mA	t _r	_	1	_	μs			
Fall Time	t _P = 20 ms	t _f	_	1	_	μs			



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TYPICAL PERFORMANCE CURVES

Fig. 1 Forward Current vs.

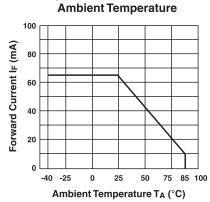


Fig. 2 Relative Radiant Intensity vs. Wavelength

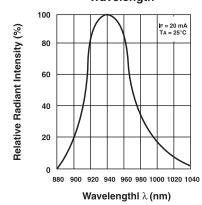


Fig. 3 Peak Emission Wavelength vs.
Ambient Temperature

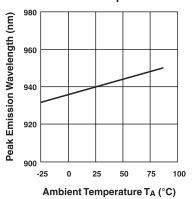


Fig. 4 Forward Current vs. Forward Voltage

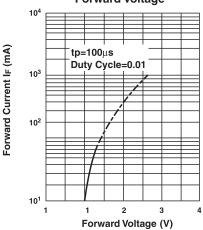


Fig. 5 Relative Intensity vs. Ambient Temperature (°C)

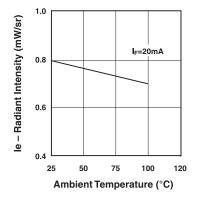
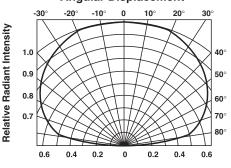


Fig. 6 Relative Radiant Intensity vs.

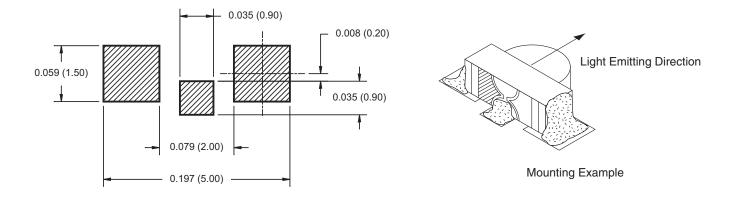
Angular Displacement



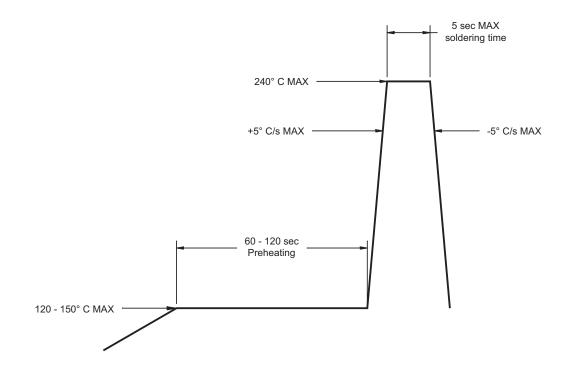


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RECOMMENDED PRINTED CIRCUIT BOARD PATTERN



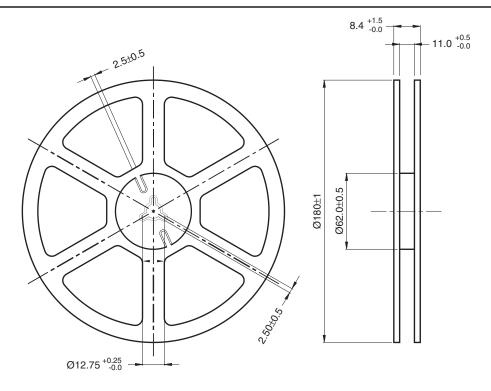
RECOMMENDED IR REFLOW SOLDERING PROFILE

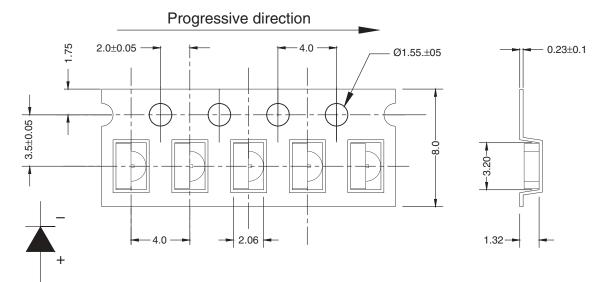




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TAPE AND REEL DIMENSIONS





Polarity Dimensional tolerance is $\pm 0.1 \text{mm}$ unless otherwise specified

Angle: ± 0.5



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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.